ICEPT-HDP 2009

2009 International Conference on Electronic Packaging Technology & High Density Packaging
The 10th Anniversary of International Conference on Electronic Packaging Technology
August 10 ~13 , 2009, Beijing, China

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CALL FOR PAPERS

On behalf of the China Electronic Packaging Society, Chinese Institute of Electronics (CIE-CEPS), it is my great pleasure to invite you to submit abstracts and attend 2009 International Conference on Electronic Packaging Technology & High Density Packaging (ICEPT-HDP 2009), to be held in Beijing, China from August 10 to 13, 2009.

Hosted by CIE-CEPS, the International Conference on Electronic Packaging Technology (ICEPT) will celebrate her 10th anniversary this year. In 1994, initiated by Tsinghua University, Fudan University, China Institute of Electronic Science, the 13th and 58th Research Institutes of CETC and others, the first International Symposium on Microelectronic Package & PCB Technology was held, which was the initiation of the ICEPT. This conference was held for nine times by 2008. They were organized in rotation by the leading universities in China, among which Tsinghua University held 3 times, and Fudan University, Harbin Institute of Technology, Huazhong University of Science & Technology, Shanghai Jiaotong University organized another 6 times. This conference has provided a great technical platform for international and domestic experts, scholars, and researchers from academia and industries to exchange their ideas on the development of electronic packaging. It was highly appreciated by China Institute of Electronics, China Association of Science, and the former Ministry of Information Industry, and greatly supported by IEEE-CPMT and IMAPS. In 2008, the ICEPT and the International Symposium on High Density Packaging (HDP), organized by Shanghai University, were merged as the International Conference on Electronic Packaging Technology & High Density Packaging (ICEPT-HDP). It was successfully held in Shanghai, China and received great appreciation and supports from both academia and industries.

ICEPT-HDP 2009 is a 4-day event, to be organized by **Tsinghua University.** The conference will feature short courses, conference keynotes, special forums and technical sessions to cover the technological developments in all the areas of electronics packaging. In conjunction with the conference, the ICEPT 10th Anniversary Celebration will be held. We sincerely invite all the leaders, experts, and peers who have been supporting this conference to come and meet in Beijing.

Keyun BI, General Chair

Vice Director General of Standing Committee of China Institute of Electronics

President of China Electronic Packaging Society

President of Packaging Branch, China Semiconductor Industrial Association

CONFERENCE THEMES

You are invited to submit an abstract, describing new development in the following themes:

- **Advanced Packaging & System Integration:** BGA, CSP, flip chip; WLP, SoP, SiP; 3D packaging, PoP, TSV; micro- & nano-system packaging; and other advanced packaging and system integration technologies.
- **High Density Substrate & SMT**: Embedded passives and active components; micro-via, micro-joint, HDI substrate, PCB, high performance multi-layer substrate; stencil print, reflow; and other novel assembly technologies that improve substrate density and performance.
- **Packaging Design and Modeling:** Various new packaging/assembly designs; methods/technologies/software for modeling, simulation and validation of electrical, thermal, optical and mechanical performance of various electronics packages; chip-packaging-PCB co-design; and multi-function & scale modeling, simulation, validation methods/software.
- **Emerging Technologies**: Sensors, actuators, MEMS, NEMS & MOEMS; optoelectronics & LED packaging; LCD, passive & RF devices, power & HV devices; nano-devices based on nano-wires, nano-tubes and polymers, etc.
- **Packaging Materials & Processes:** New developments in bonding wires, solders, underfills, encapsulations, adhesives, thin films, dielectrics, substrate materials; green electronics materials, nanomaterials and other novel materials for packaging performance enhancement and cost reduction; and various packaging/assembly processes.
- **Packaging Equipment & Advanced Manufacturing Technologies:** New packaging/assembly equipment; packaging equipment/measurement techniques for emerging technologies; photolithography, laser processing; novel packaging/assembly technologies for manufacturability and yield improvement, cost reduction and service performance improvement; and methods/software for modeling and monitoring of process effectiveness & cost analysis.
- **Quality & Reliability:** Quality monitoring and evaluation for packaging/assembly; advanced methods/technologies/tools for rapid reliability data collection/analysis, reliability modeling & life prediction; reliability issues in various electronics packages; and new methods/technologies/tools for failure analysis.

IMPORTANT DATES

- **April 6, 2009 – Deadline for Submission of Abstract**
- **April 20, 2009 – Notification of Acceptance**
- **July 13 , 2009 – Deadline for Submission of Manuscript**

SUBMISSION OF ABSTRACT/PAPER

Abstracts are solicited to describe original and unpublished work. The abstract should be approx. 500 words and contains a clear statement of the background, methodology, results, conclusions, and important references of the work. All abstracts must be in English and should be submitted using the format provided in the attached word file to icept2009@tsinghua.edu.cn.

The abstracts must be received by **April 6, 2009.** Authors must include their affiliations, mailing addresses, telephone and fax numbers, and email addresses. Authors will be notified of paper acceptance by **April 20, 2009.** The final manuscripts for publication in the conference proceedings are due by **July 13, 2009.** Selected papers will be recommended for publication in IEEE/CPMT journals.

CALL FOR EXHIBITION/SPONSORSHIP

A tabletop exhibition featuring suppliers of materials, equipment, components and software, manufacturers, and service providers of the electronics packaging and related industries will be held during the conference. Potential exhibitors and sponsors may email icept2009@tsinghua.edu.cn for details.

Conference Website: http://www.icept.org

Conference Contacts: icept2009@tsinghua.edu.cn